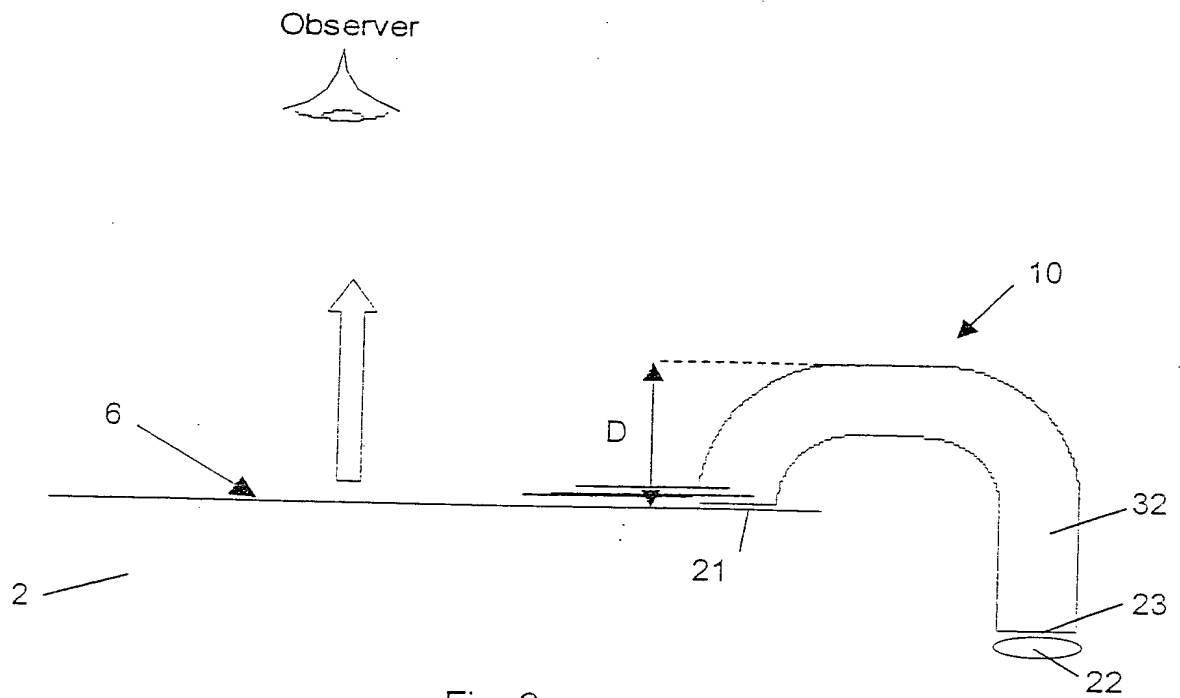
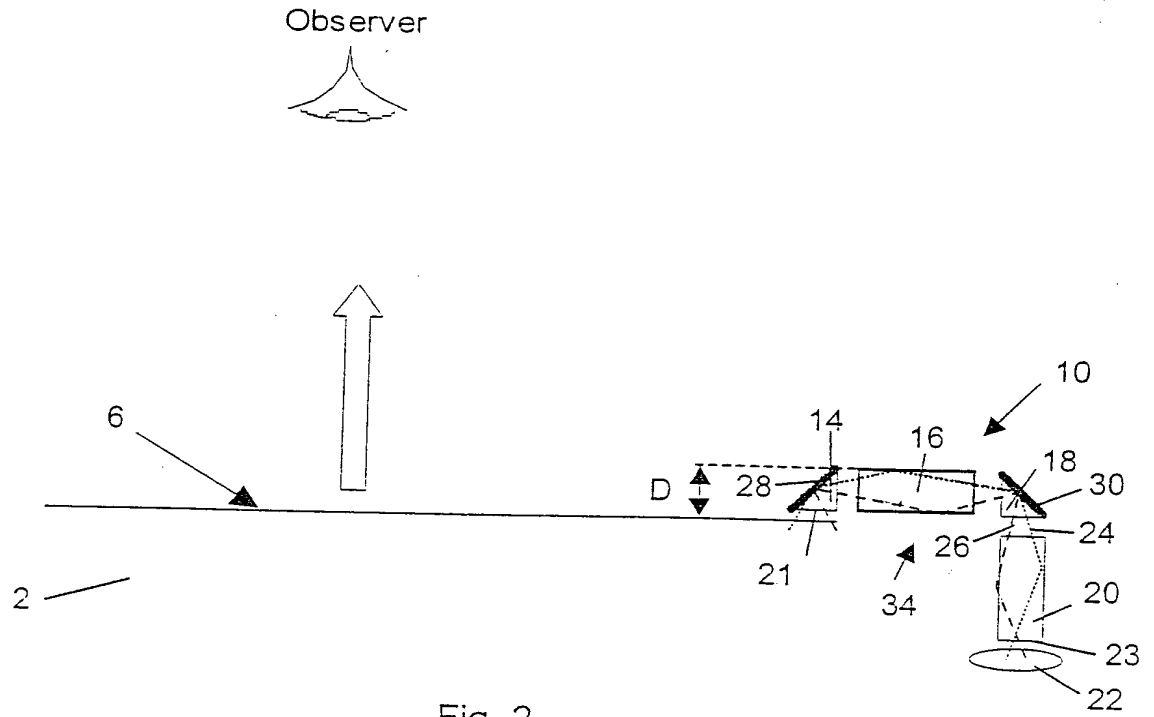


A cross-sectional view of a substrate 1. A thin layer 2 is formed on the top surface of the substrate 1. A conductive pattern 8 is formed on the top surface of the thin layer 2. The conductive pattern 8 is composed of a central rectangular portion and two side portions. The side portions are connected to the central portion by narrow bridges. A lead 10 is formed on the bottom surface of the substrate 1, extending from the central portion of the conductive pattern 8.

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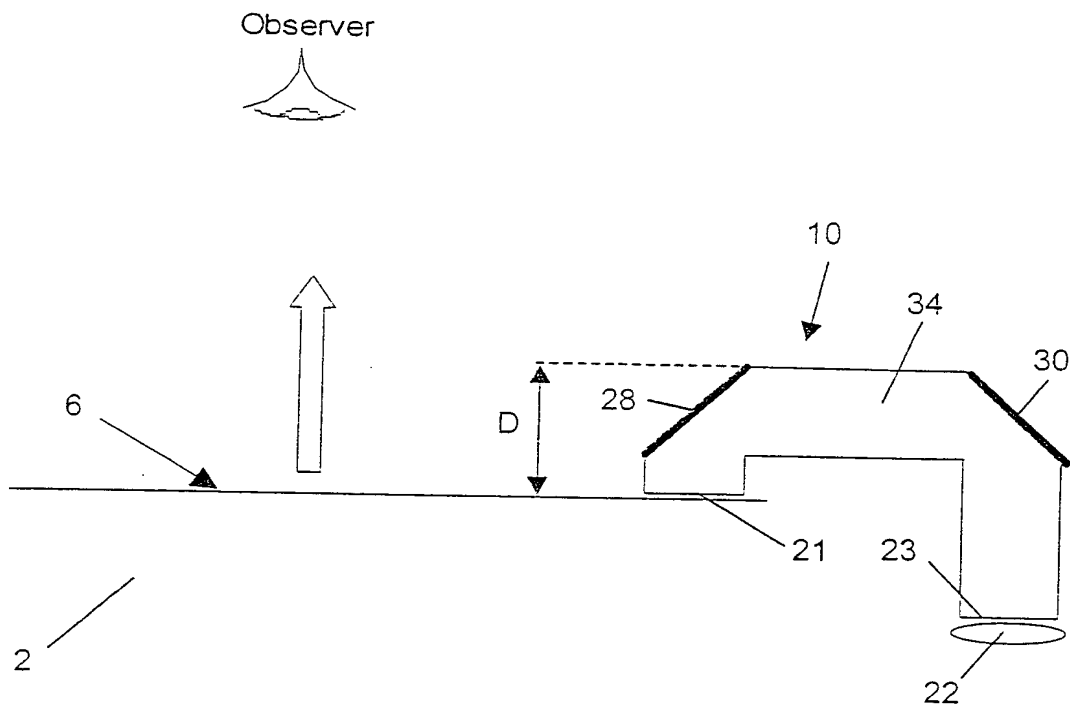


Fig. 4

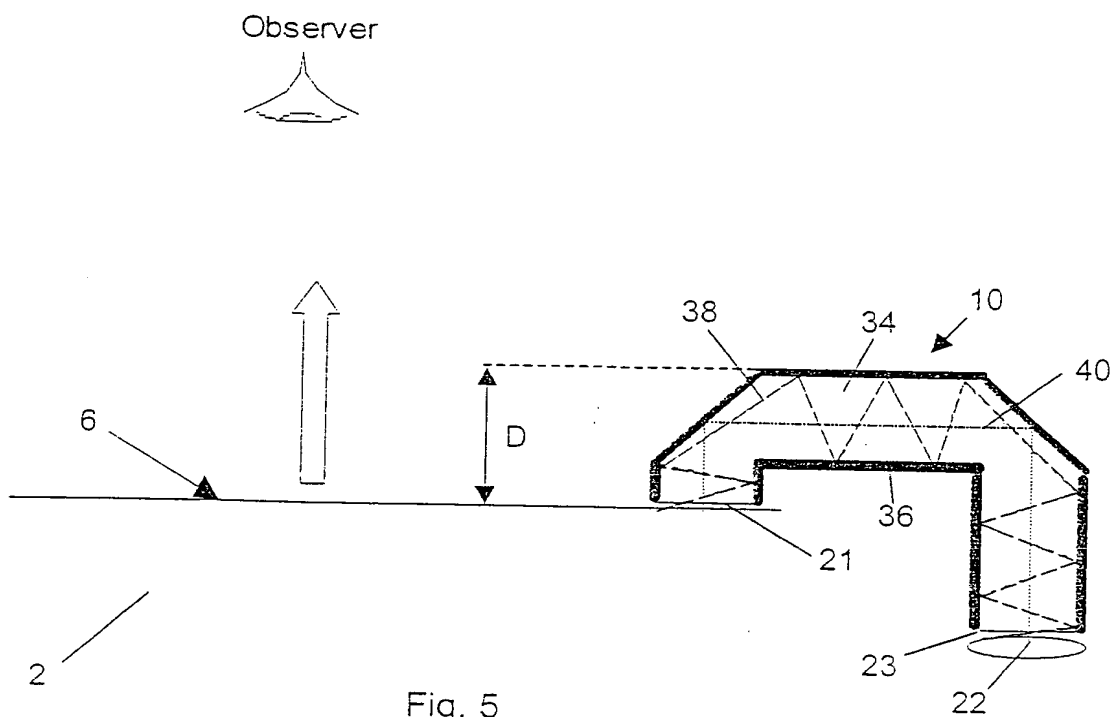


Fig. 5

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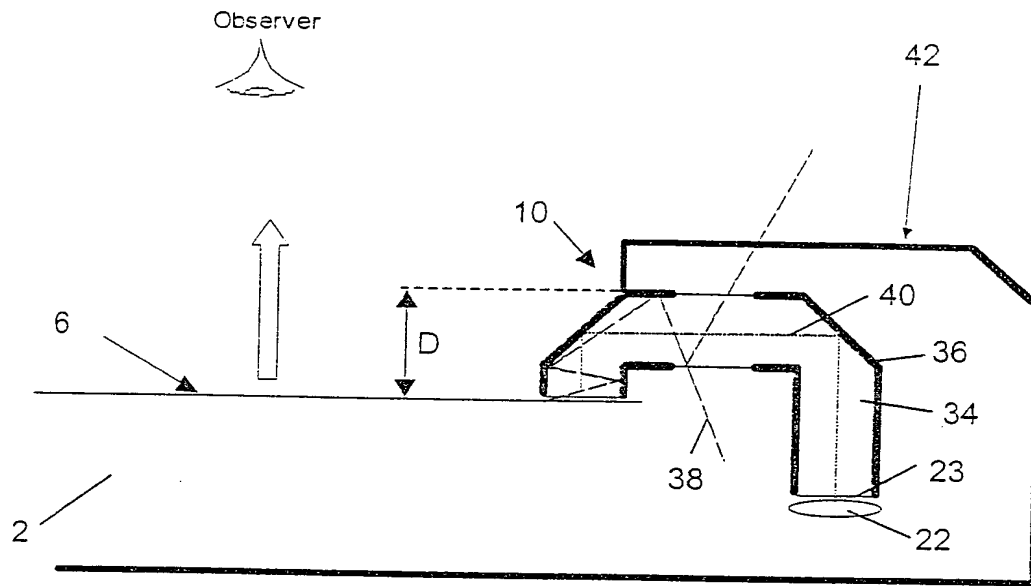


Fig. 6

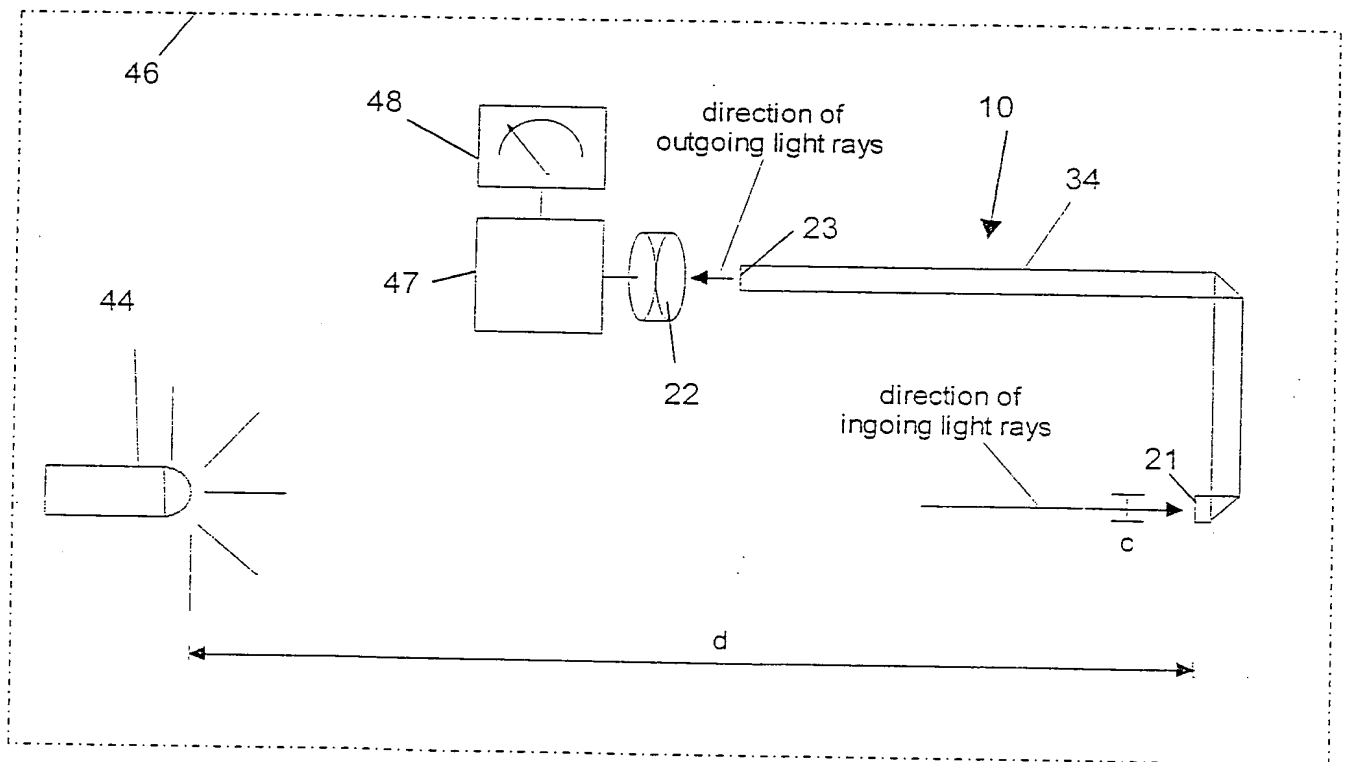


Fig. 7

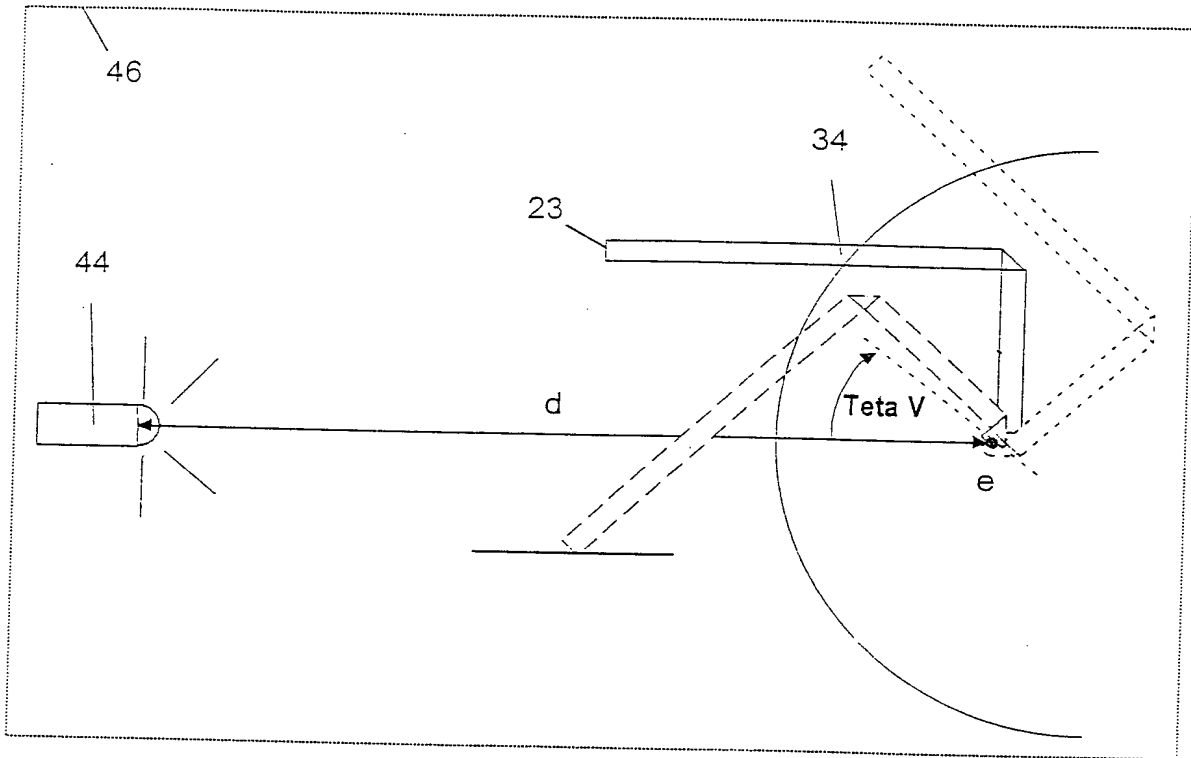


Fig. 8

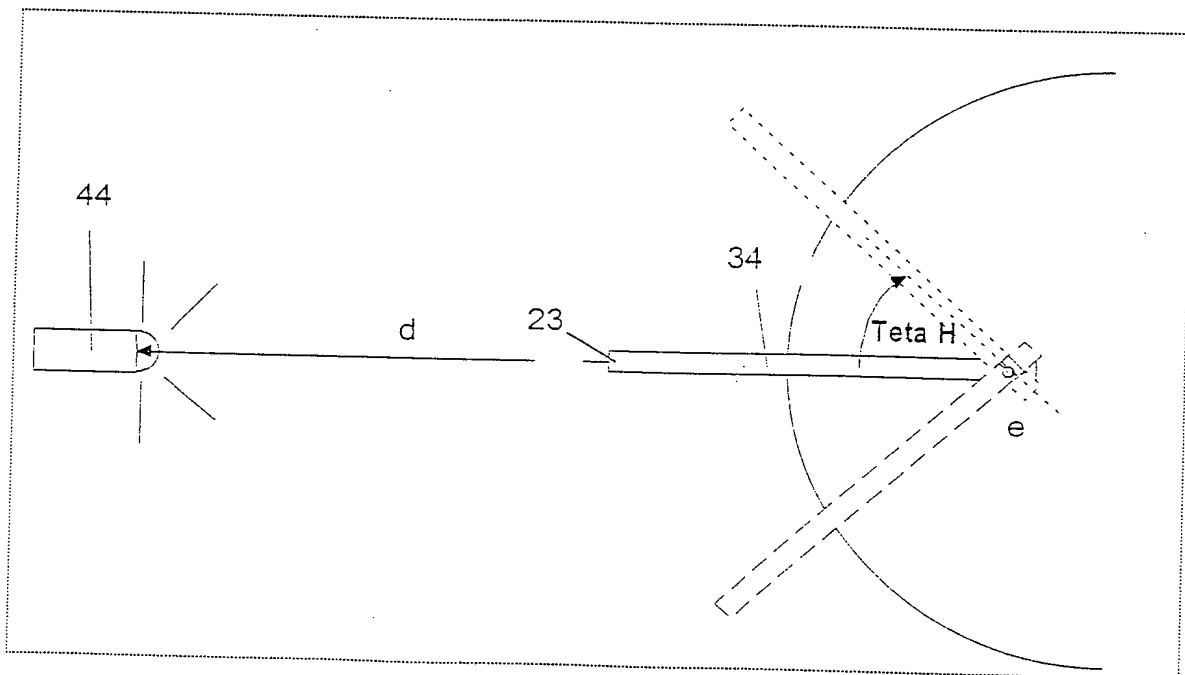


Fig. 9

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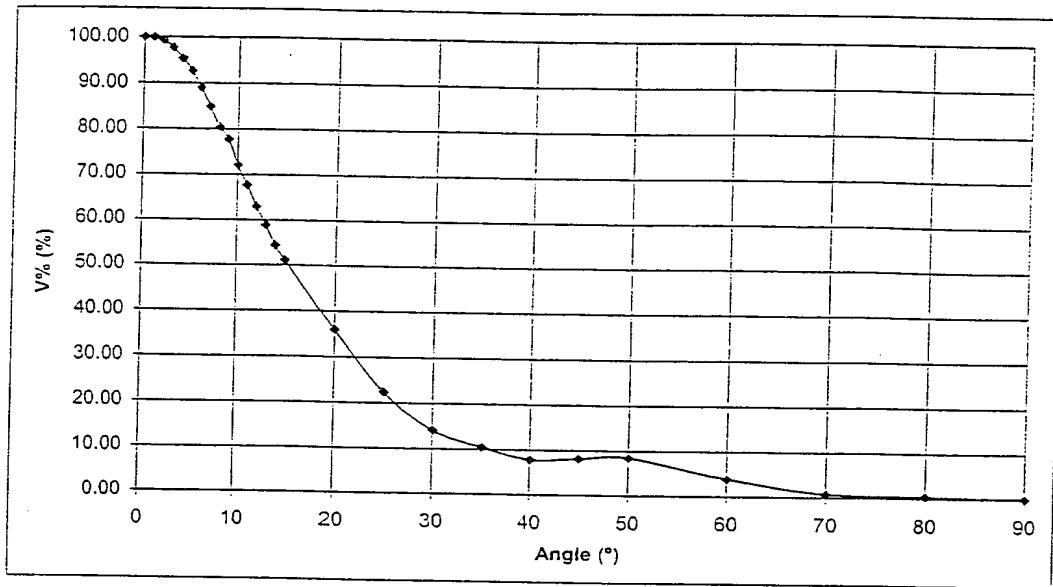


Fig. 10A

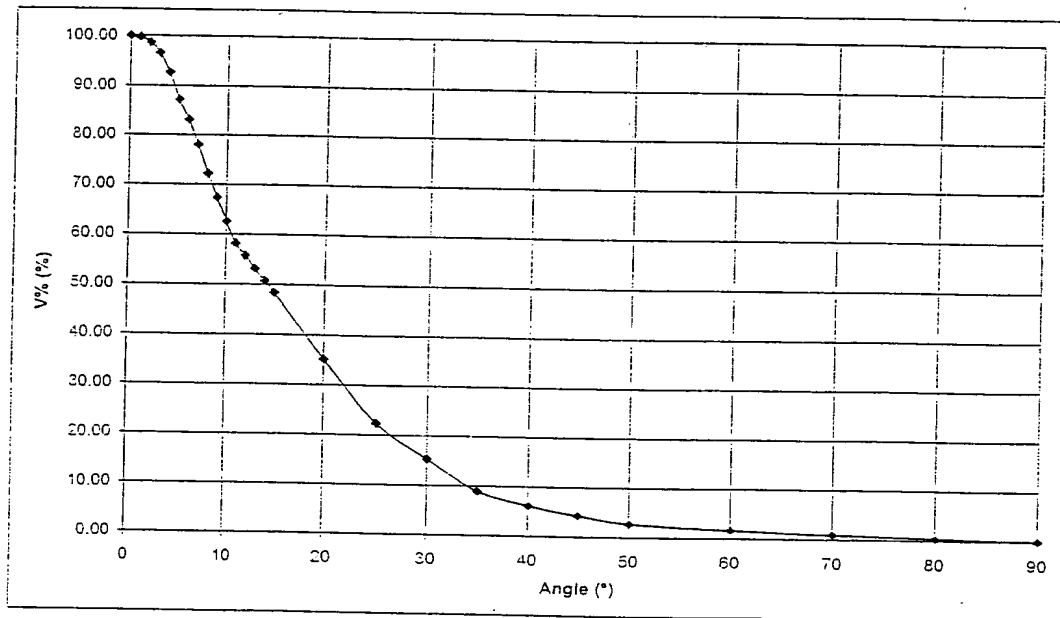


Fig. 10B